

Copper

SLOTOCOUP CU 210

Copper SLOTOCOUP CU 210 allows in conjunction with Reverse Pulse Plating an excellent metal distribution in through holes. The copper coatings deposited are fine-grained and ductile. Since higher current densities are possible than in DC plating, a considerable reduction of the plating time with excellent metal distribution can be achieved at the same time.

The electrolyte is made-up and operated with two additives.

SLOTOCOUP CU 210 can also be operated as a traditional DC plating (direct current) electrolyte, then it deposits bright, fine-grained, ductile copper deposits.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

